

### **Abstract of the Disclosure**

The present invention provides a semiconductor device which comprises a die pad section (200) having a surface (201) and a back surface (202), a first semiconductor chip (4) having a surface (41) on which a first electrode section (47) is formed, and a back surface (42) fixed to the surface of the die pad section (200), a second semiconductor chip (5) having a surface (51) on which a second electrode section (57) is formed, and a back surface (52) fixed to the surface (41) of the first semiconductor chip (4), lead terminal sections (210 and 220) respectively electrically connected to the first and second electrode sections (47 and 57), and a resin encapsulating body (10) that seals the die pad section (200) and the first and second semiconductor chips (4 and 5). An edge portion (54) of the second semiconductor chip (5) protrudes from an edge portion (44) of the first semiconductor chip (4). An edge portion (204) of the die pad section (200) protrudes from an edge portion (44) of the first semiconductor chip (4).